L Number	Hits	Search Text	DB	Time stamp
1	591015	(plate or board or substrate or article) near5 (resin$5 or polymer$5 or plastic or polyimide or non$2conduct$8 or insulat$8 or epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 10:46
2	129791	((plate or board or substrate or article) near5 (resin$5 or polymer$5 or plastic or polyimide or non$2conduct$8 or insulat$8 or epoxy)) and ((plate or board or substrate or article) near5 (via$3 or hole$3 or opening$3 or trench$3 or recess$3 or cavit$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 10:47
3	10	"13" and (electroless$3 near15 (via$3 or hole$3 or opening$3 or trench$3 or recess$3 or cavit$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 10:53
4	1851	(((plate or board or substrate or article) near5 (resin$5 or polymer$5 or plastic or polyimide or non$2conduct$8 or insulat$8 or epoxy)) and ((plate or board or substrate or article) near5 (via$3 or hole$3 or opening$3 or trench$3 or recess$3 or cavit$6))) and (electroless$3 near15 (via$3 or hole$3 or opening$3 or trench$3 or recess$3 or cavit$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 10:53
5	951	((((plate or board or substrate or article) near5 (resin$5 or polymer$5 or plastic or polyimide or non$2conduct$8 or insulat$8 or epoxy)) and ((plate or board or substrate or article) near5 (via$3 or hole$3 or opening$3 or trench$3 or recess$3 or cavit$6))) and (electroless$3 near15 (via$3 or hole$3 or opening$3 or trench$3 or recess$3 or cavit$6))) and ((electroplat$10 or electrodeposit$10 or electroly$10 or electrochem$10) near15 (via$3 or hole$3 or opening$3 or trench$3 or recess$3 or cavit$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 10:54
6	498	(((((plate or board or substrate or article) near5 (resin$5 or polymer$5 or plastic or polyimide or non$2conduct$8 or insulat$8 or epoxy)) and ((plate or board or substrate or article) near5 (via$3 or hole$3 or opening$3 or trench$3 or recess$3 or cavit$6))) and (electroless$3 near15 (via$3 or hole$3 or opening$3 or trench$3 or recess$3 or cavit$6))) and ((electroplat$10 or electrodeposit$10 or electroly$10 or electrochem$10) near15 (via$3 or hole$3 or opening$3 or trench$3 or recess$3 or cavit$6))) and wiring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 10:54
7	135	((((((plate or board or substrate or article) near5 (resin$5 or polymer$5 or plastic or polyimide or non$2conduct$8 or insulat$8 or epoxy)) and ((plate or board or substrate or article) near5 (via$3 or hole$3 or opening$3 or trench$3 or recess$3 or cavit$6))) and (electroless$3 near15 (via$3 or hole$3 or opening$3 or trench$3 or recess$3 or cavit$6))) and ((electroplat$10 or electrodeposit$10 or electroly$10 or electrochem$10) near15 (via$3 or hole$3 or opening$3 or trench$3 or recess$3 or cavit$6))) and wiring) and polish$10	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 12:00

C.\APPS\east\workspaces\default.wsp

9	11419	solder adj balls	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 12:06
10	4372	((plate or board or substrate or article) near5 (resin$5 or polymer$5 or plastic or polyimide or non$2conduct$8 or insulat$8 or epoxy)) and (solder adj balls)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 12:07
11	4009	(((plate or board or substrate or article) near5 (resin$5 or polymer$5 or plastic or polyimide or non$2conduct$8 or insulat$8 or epoxy)) and (solder adj balls)) and (via$3 or trench$3 or hole$3 or opening$3 or recess$3 or groove$3 or cavit$8)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 12:07
12	1799	((((plate or board or substrate or article) near5 (resin$5 or polymer$5 or plastic or polyimide or non$2conduct$8 or insulat$8 or epoxy)) and (solder adj balls)) and (via$3 or trench$3 or hole$3 or opening$3 or recess$3 or groove$3 or cavit$8)) and wiring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 12:09
13	1496	(((((plate or board or substrate or article) near5 (resin$5 or polymer$5 or plastic or polyimide or non$2conduct$8 or insulat$8 or epoxy)) and (solder adj balls)) and (via$3 or trench$3 or hole$3 or opening$3 or recess$3 or groove$3 or cavit$8)) and wiring) and pad$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 12:08
15	93	((((((plate or board or substrate or article) near5 (resin$5 or polymer$5 or plastic or polyimide or non$2conduct$8 or insulat$8 or epoxy)) and (solder adj balls)) and (via$3 or trench$3 or hole$3 or opening$3 or recess$3 or groove$3 or cavit$8)) and wiring) and pad$3) and (press$2forming or (injection adj mold$5))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 12:09
16	90	(((((((plate or board or substrate or article) near5 (resin$5 or polymer$5 or plastic or polyimide or non$2conduct$8 or insulat$8 or epoxy)) and (solder adj balls)) and (via$3 or trench$3 or hole$3 or opening$3 or recess$3 or groove$3 or cavit$8)) and wiring) and pad$3) and (press$2forming or (injection adj mold$5))) not ((((((plate or board or substrate or article) near5 (resin$5 or polymer$5 or plastic or polyimide or non$2conduct$8 or insulat$8 or epoxy)) and ((plate or board or substrate or article) near5 (via$3 or hole$3 or opening$3 or trench$3 or recess$3 or cavit$6))) and (electroless$3 near15 (via$3 or hole$3 or opening$3 or trench$3 or recess$3 or cavit$6))) and ((electroplat$10 or electrodeposit$10 or electroly$10 or electrochem$10) near15 (via$3 or hole$3 or opening$3 or trench$3 or recess$3 or cavit$6))) and wiring) and polish$10)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 12:09